

# BC848 series

30 V, 100 mA NPN general-purpose transistors

Rev. 07 — 17 November 2009

Product data sheet

## 1. Product profile

### 1.1 General description

NPN general-purpose transistors in Surface Mounted Device (SMD) plastic packages.

Table 1. Product overview

Type number	Package			PNP complement
	NXP	JEITA	JEDEC	
BC848B	SOT23	-	TO-236AB	BC858B
BC848W	SOT323	SC-70	-	BC858W

### 1.2 Features

- General-purpose transistors
- SMD plastic packages

### 1.3 Applications

- General-purpose switching and amplification

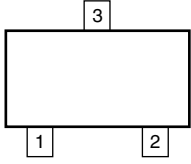
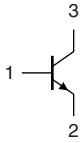
### 1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CE0}$	collector-emitter voltage	open base	-	-	30	V
$I_C$	collector current		-	-	100	mA
$h_{FE}$	DC current gain	$V_{CE} = 5\text{ V};$ $I_C = 2\text{ mA}$				
	BC848B		200	290	450	
	BC848W		110	-	800	

## 2. Pinning information

**Table 3. Pinning**

Pin	Description	Simplified outline	Symbol
1	base	 <p>006aaa144</p>	 <p>sym021</p>
2	emitter		
3	collector		

## 3. Ordering information

**Table 4. Ordering information**

Type number	Package		
	Name	Description	Version
BC848B	-	plastic surface mounted package; 3 leads	SOT23
BC848W	SC-70	plastic surface mounted package; 3 leads	SOT323

## 4. Marking

**Table 5. Marking codes**

Type number	Marking code <sup>[1]</sup>
BC848B	1K*
BC848W	1M*

- [1] \* = -: made in Hong Kong  
 \* = p: made in Hong Kong  
 \* = t: made in Malaysia  
 \* = W: made in China

## 5. Limiting values

**Table 6. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	30	V
$V_{CEO}$	collector-emitter voltage	open base	-	30	V
$V_{EBO}$	emitter-base voltage	open collector	-	5	V
$I_C$	collector current		-	100	mA
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms	-	200	mA
$I_{BM}$	peak base current	single pulse; $t_p \leq 1$ ms	-	200	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C	[1]		
	SOT23		-	250	mW
	SOT323		-	200	mW
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-65	+150	°C
$T_{stg}$	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

## 6. Thermal characteristics

**Table 7. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]			
	SOT23		-	-	500	K/W
	SOT323		-	-	625	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

## 7. Characteristics

**Table 8. Characteristics**

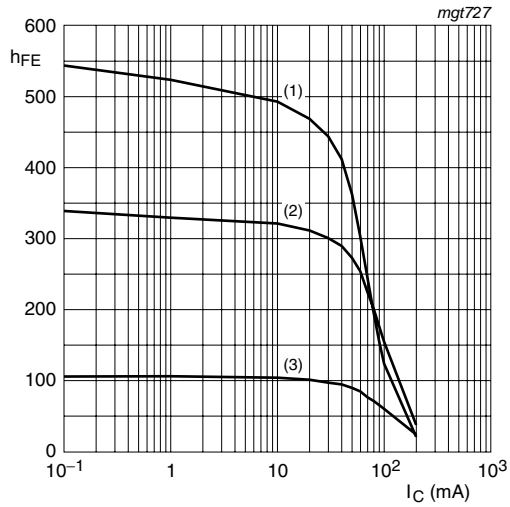
$T_{amb} = 25\text{ °C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$I_{CBO}$	collector-base cut-off current	$V_{CB} = 30\text{ V}; I_E = 0\text{ A}$	-	-	15	nA	
		$V_{CB} = 30\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ °C}$	-	-	5	$\mu\text{A}$	
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = 5\text{ V}; I_E = 0\text{ A}$	-	-	100	nA	
$h_{FE}$	DC current gain	$V_{CE} = 5\text{ V}; I_C = 10\text{ }\mu\text{A}$	-	150	-		
		$V_{CE} = 5\text{ V}; I_C = 2\text{ mA}$					
		BC848B	200	290	450		
		BC848W	110	-	800		
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 10\text{ mA}; I_B = 0.5\text{ mA}$	-	90	250	mV	
		$I_C = 100\text{ mA}; I_B = 5\text{ mA}$	[1]	-	200	600	mV
$V_{BEsat}$	base-emitter saturation voltage	$I_C = 10\text{ mA}; I_B = 0.5\text{ mA}$	[2]	-	700	-	mV
		$I_C = 100\text{ mA}; I_B = 5\text{ mA}$	[2]	-	900	-	mV
$V_{BE}$	base-emitter voltage	$I_C = 2\text{ mA}; V_{CE} = 5\text{ V}$	[3]	580	660	700	mV
		$I_C = 10\text{ mA}; V_{CE} = 5\text{ V}$	[3]	-	-	770	mV
$f_T$	transition frequency	$V_{CE} = 5\text{ V}; I_C = 10\text{ mA}; f = 100\text{ MHz}$	100	-	-	MHz	
$C_C$	collector capacitance	$V_{CB} = 10\text{ V}; I_E = i_e = 0\text{ A}; f = 1\text{ MHz}$	-	2.5	3	pF	
NF	noise figure	$V_{CE} = 5\text{ V}; I_C = 200\text{ }\mu\text{A}; R_S = 2\text{ k}\Omega; f = 1\text{ kHz}; B = 200\text{ Hz}$	-	2	10	dB	

[1] Pulse test:  $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$ .

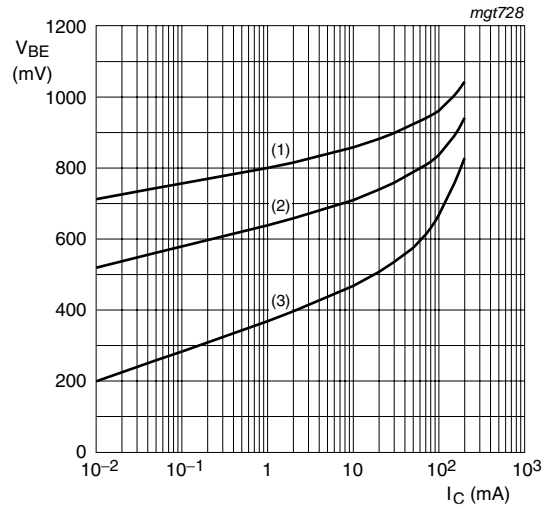
[2]  $V_{BEsat}$  decreases by approximately 1.7 mV/K with increasing temperature.

[3]  $V_{BE}$  decreases by approximately 2 mV/K with increasing temperature.



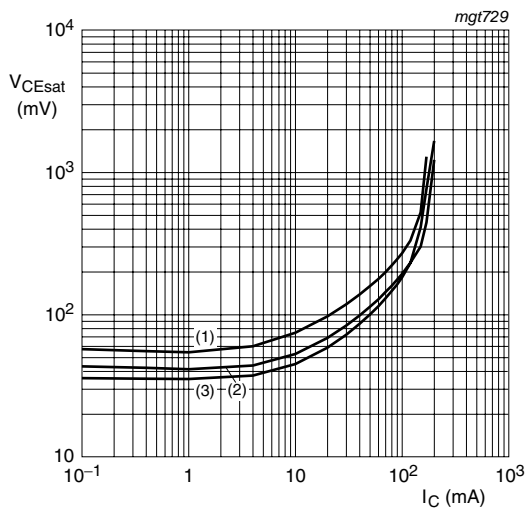
$V_{CE} = 5\text{ V}$   
 (1)  $T_{amb} = 150\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -55\text{ °C}$

**Fig 1. BC848B: DC current gain as a function of collector current; typical values**



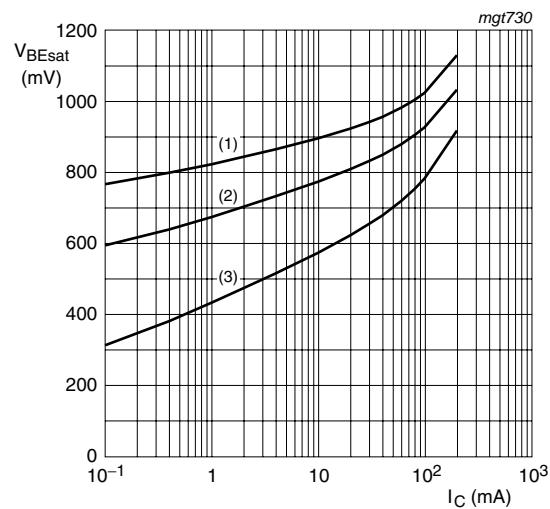
$V_{CE} = 5\text{ V}$   
 (1)  $T_{amb} = -55\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = 150\text{ °C}$

**Fig 2. BC848B: Base-emitter voltage as a function of collector current; typical values**



$I_C/I_B = 20$   
 (1)  $T_{amb} = 150\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -55\text{ °C}$

**Fig 3. BC848B: Collector-emitter saturation voltage as a function of collector current; typical values**



$I_C/I_B = 10$   
 (1)  $T_{amb} = -55\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = 150\text{ °C}$

**Fig 4. BC848B: Base-emitter saturation voltage as a function of collector current; typical values**

## 8. Package outline

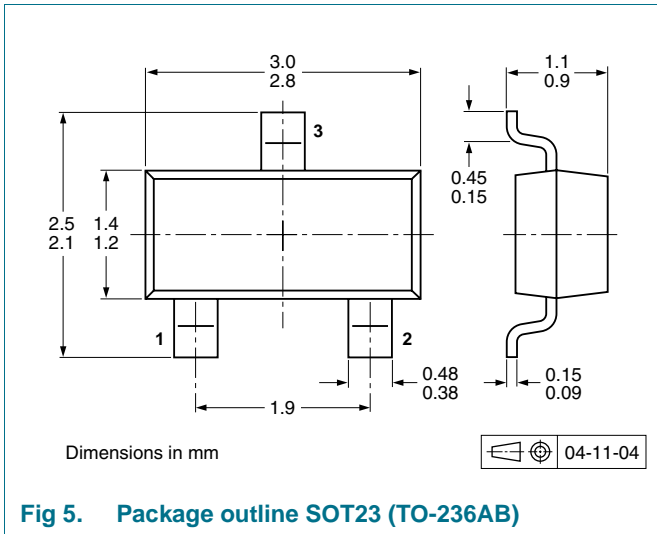


Fig 5. Package outline SOT23 (TO-236AB)

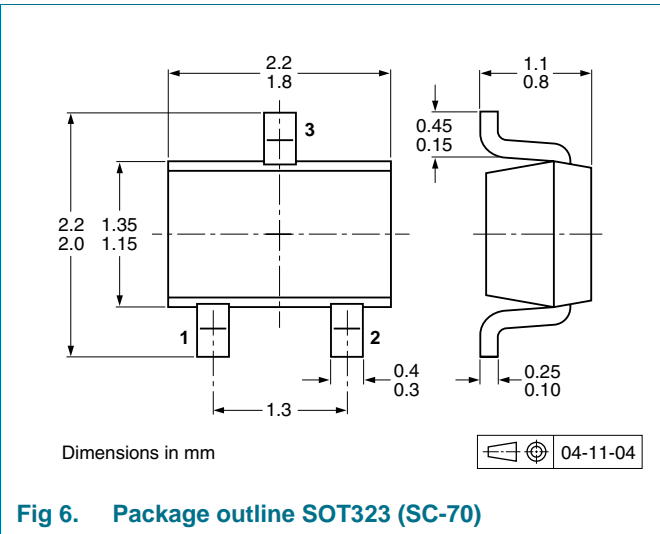


Fig 6. Package outline SOT323 (SC-70)

## 9. Packing information

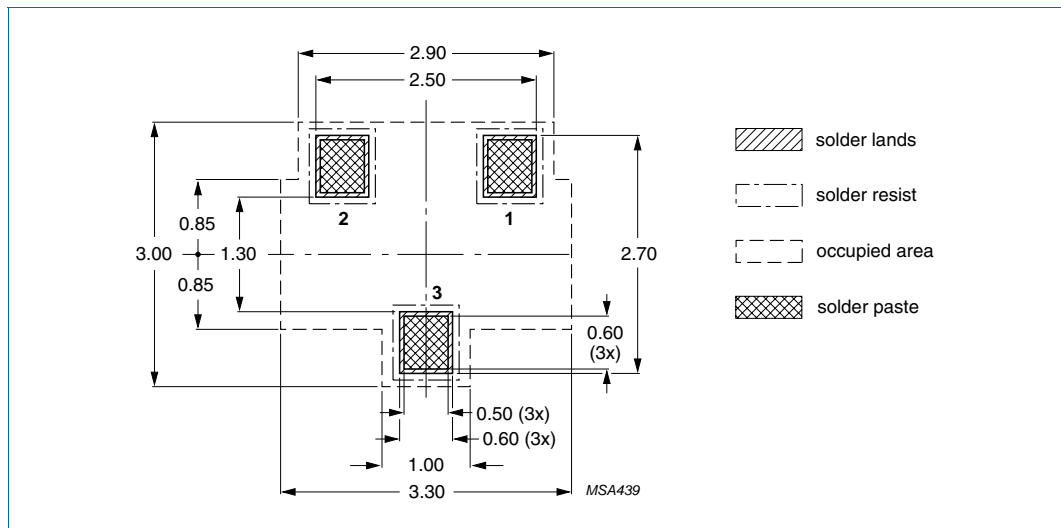
Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity	
			3000	10000
BC848B	SOT23	4 mm pitch, 8 mm tape and reel	-215	-235
BC848W	SOT323	4 mm pitch, 8 mm tape and reel	-115	-135

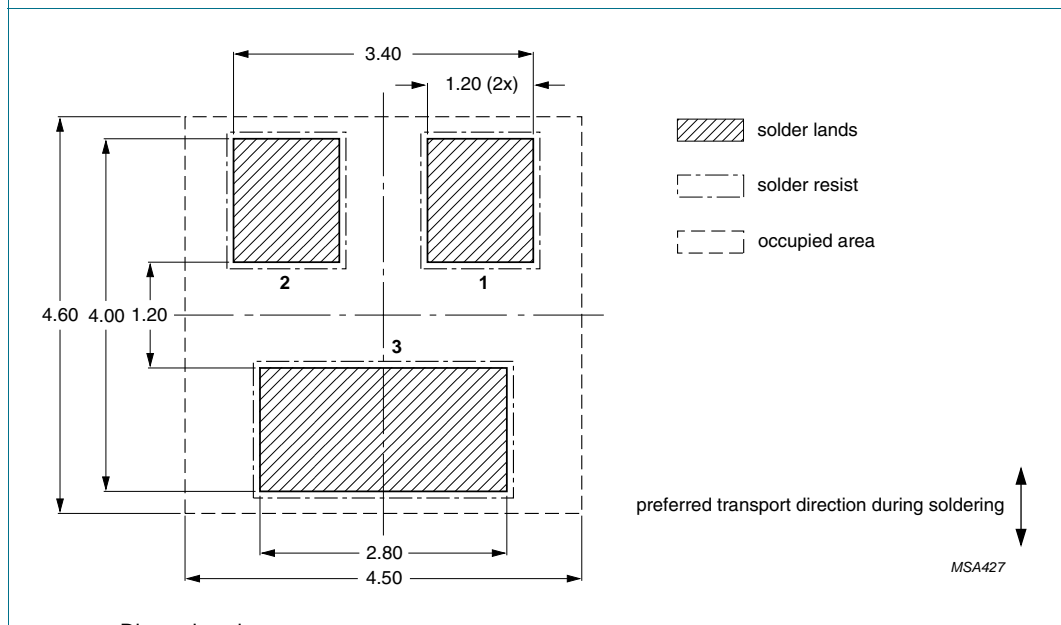
[1] For further information and the availability of packing methods, see [Section 14](#).

10. Soldering



Dimensions in mm

Fig 7. Reflow soldering footprint SOT23 (TO-236AB)



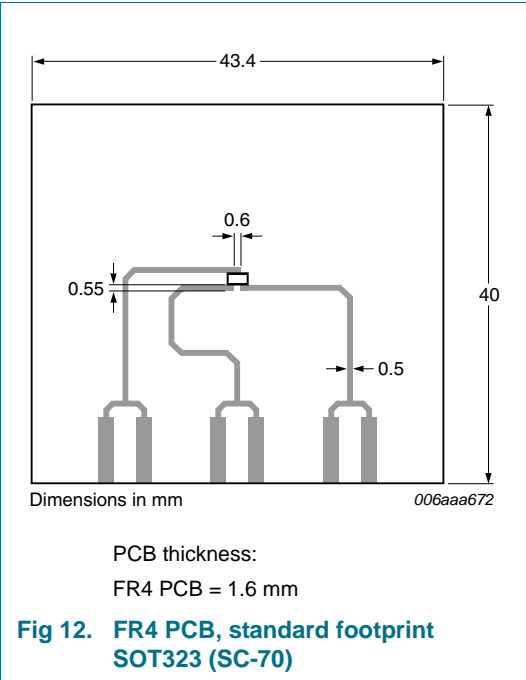
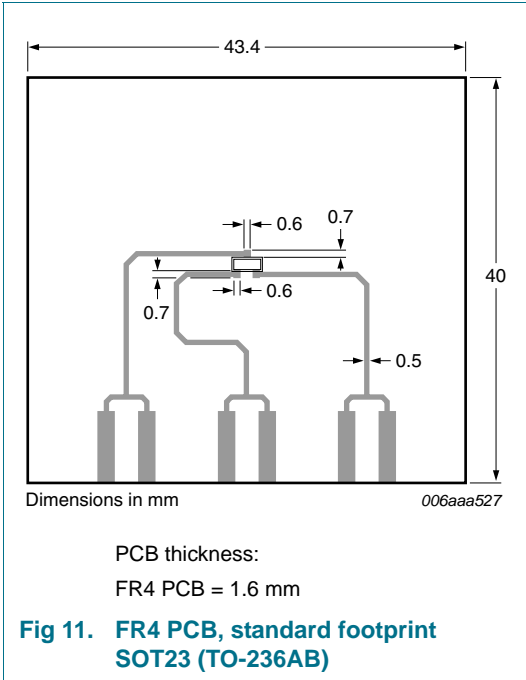
Dimensions in mm

Fig 8. Wave soldering footprint SOT23 (TO-236AB)





11. Mounting



## 12. Revision history

**Table 10. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
BC848_SER_7	20091117	Product data sheet	-	BC848_SER_6
Modifications:	<ul style="list-style-type: none"> <li>• This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.</li> <li>• <a href="#">Figure 9 “Reflow soldering footprint SOT323 (SC-70)”</a>: updated</li> <li>• <a href="#">Figure 10 “Wave soldering footprint SOT323 (SC-70)”</a>: updated</li> </ul>			
BC848_SER_6	20060203	Product data sheet	-	BC846_BC847_ BC848_5 BC846W_BC847W_ BC848W_4
BC846_BC847_BC848_5	20040206	Product specification	-	BC846_BC847_ BC848_4
BC846W_BC847W_ BC848W_4	20020204	Product specification	-	BC846W_847W_3

## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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**15. Contents**

**1 Product profile . . . . . 1**

1.1 General description . . . . . 1

1.2 Features . . . . . 1

1.3 Applications . . . . . 1

1.4 Quick reference data . . . . . 1

**2 Pinning information . . . . . 2**

**3 Ordering information . . . . . 2**

**4 Marking . . . . . 2**

**5 Limiting values . . . . . 3**

**6 Thermal characteristics . . . . . 3**

**7 Characteristics . . . . . 4**

**8 Package outline . . . . . 6**

**9 Packing information . . . . . 6**

**10 Soldering . . . . . 7**

**11 Mounting . . . . . 9**

**12 Revision history . . . . . 10**

**13 Legal information . . . . . 11**

13.1 Data sheet status . . . . . 11

13.2 Definitions . . . . . 11

13.3 Disclaimers . . . . . 11

13.4 Trademarks . . . . . 11

**14 Contact information . . . . . 11**

**15 Contents . . . . . 12**

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